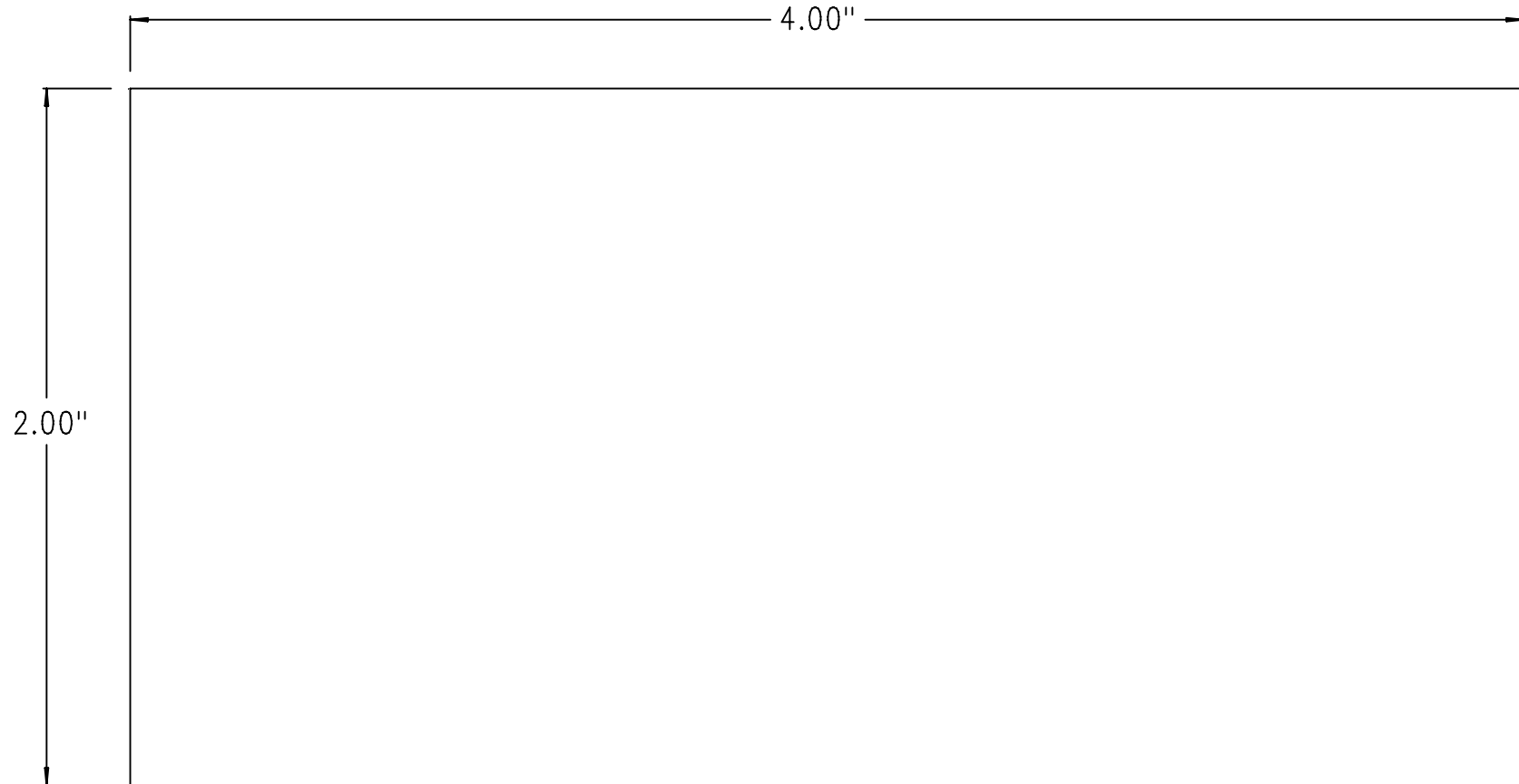


ALL DIMENSIONS ARE IN INCHES +/- 0.005 UNLESS OTHERWISE SPECIFIED
Reference TI Document 87-00020 for Quality Assurance Requirements



Substrate material:	Grade FR-406, UL certified 94V-0, 170°C or greater.	Surface Finish:	ENIG; Plate with a minimum of 3-8 microinches of gold over a minimum of 150 microinches of electroless nickel.
Circuitry material and thickness:	Copper (2 oz), finished on all layers 0.002" Plating in holes.	Vendor marking:	On bottom side solder mask.
Overall thickness:	0.062" +/-0.005"	Legend:	White non-conductive photo-imageable epoxy ink
		Solder mask:	Both Sides with Blue Liquid Photo-Imagable (LPI), SMOBC

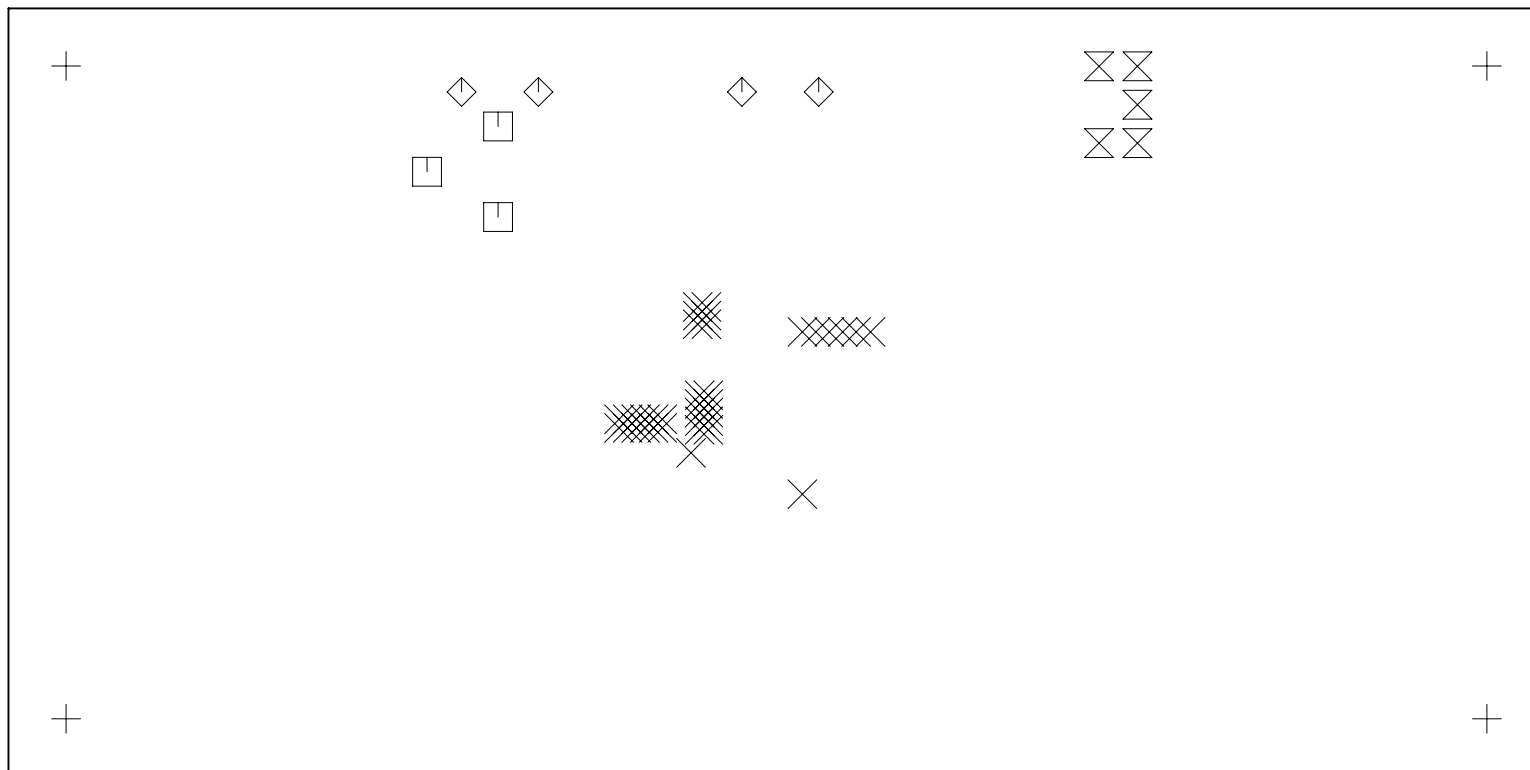


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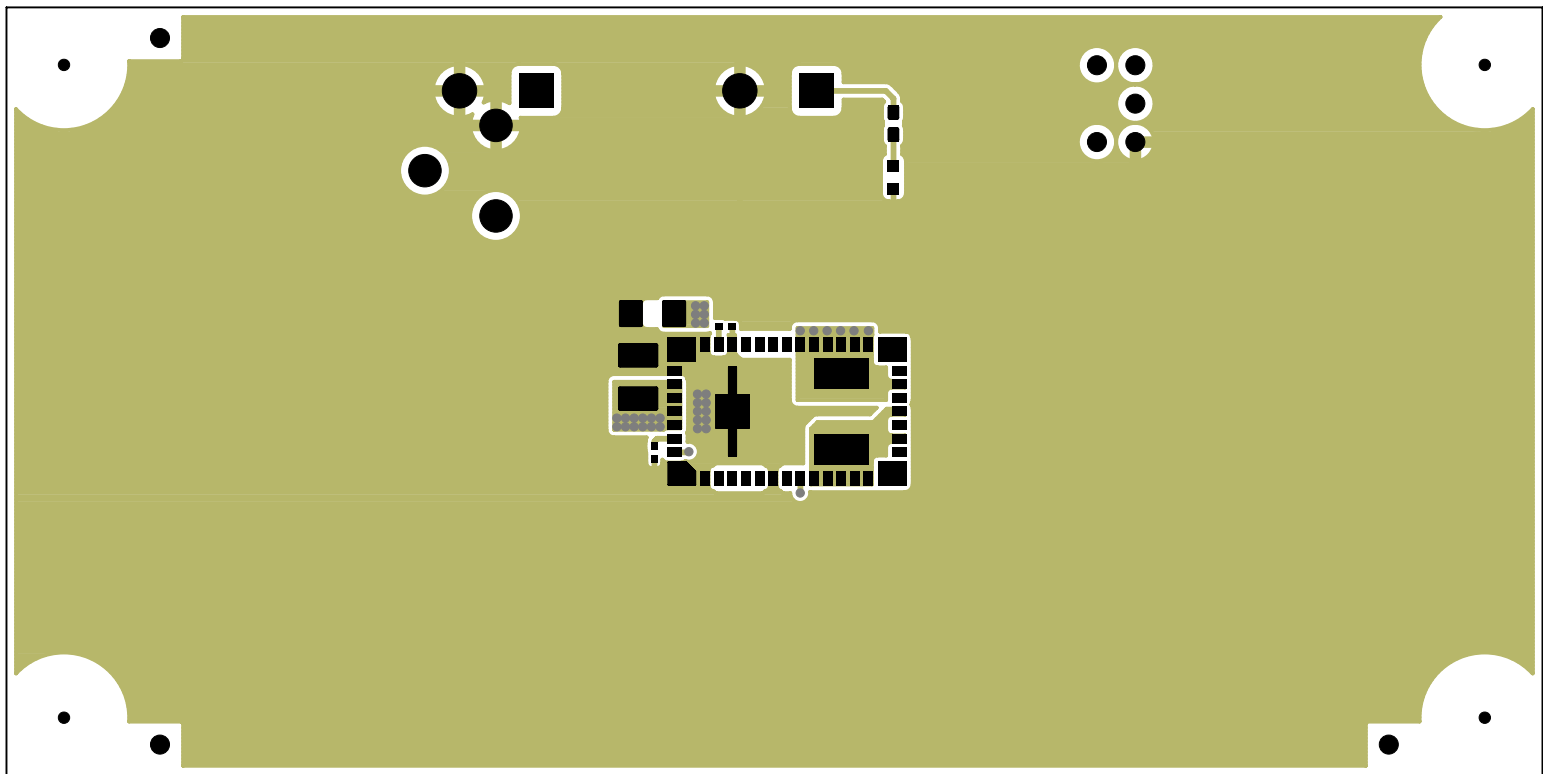
FILENAME
1011-1C.PCB

DESCRIPTION		DWG NO	
PCB, FR-406, TPS84620 DEMO BOARD		74-01011	
DRAWN	DATE	REV	REFERENCE NUMBER
		1C	PMP5785
CHECKED	DATE	SIZE	SCALE
		A	2:1
ISSUED	DATE	DO NOT SCALE DRAWING	
		PAGE 1 OF 9	

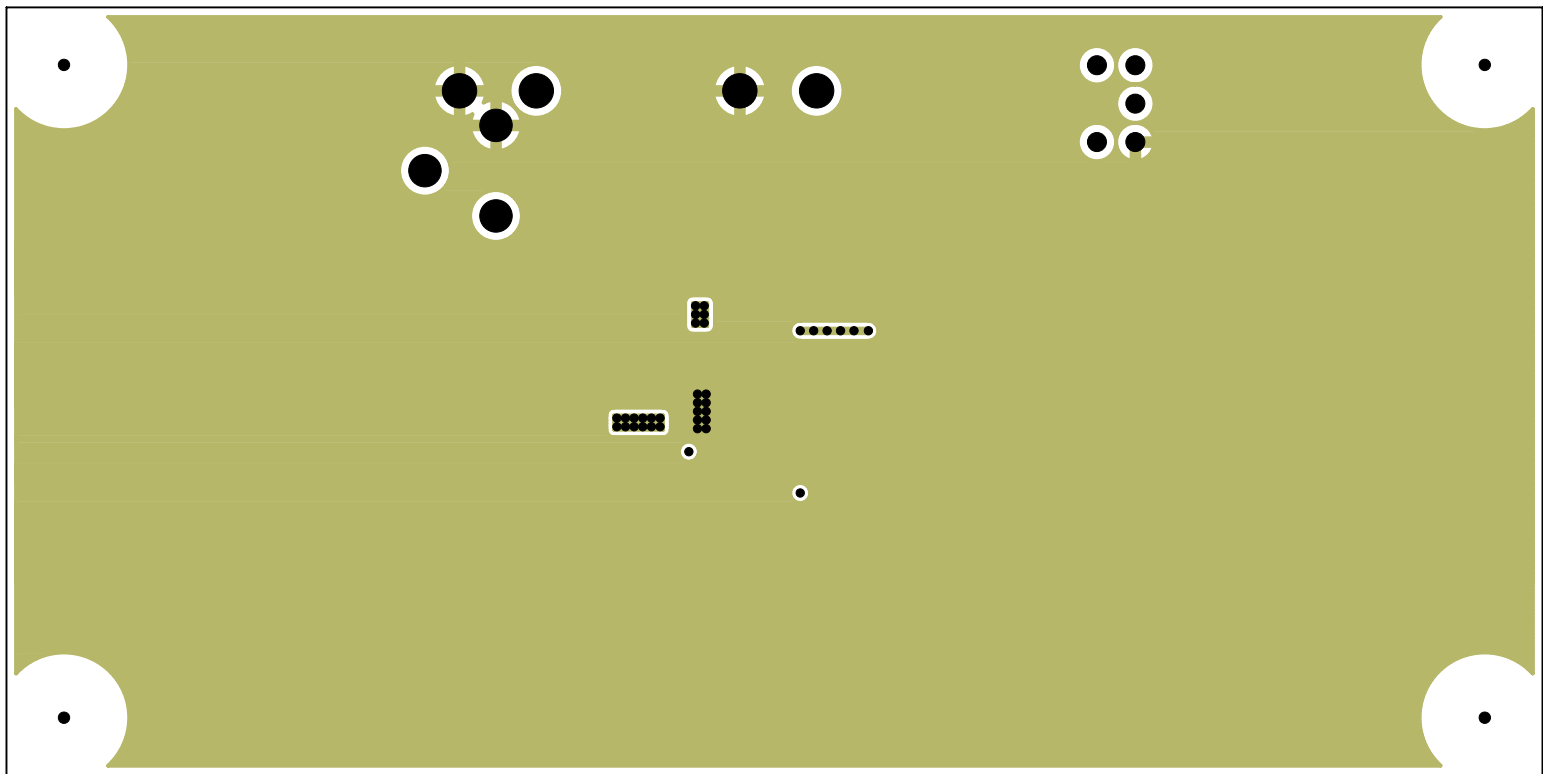


FINISHED HOLE SIZES
DIMENSIONS ARE IN INCHES

SIZE	QTY	SYM	PLATED	TOL
0.012	36	⊠	YES	+0.003/-0.012
0.026	5	⊠	YES	+/-0.003
0.052	4	◇	YES	+/-0.003
0.055	3	□	YES	+/-0.003
0.159	4	+	NO	+/-0.002

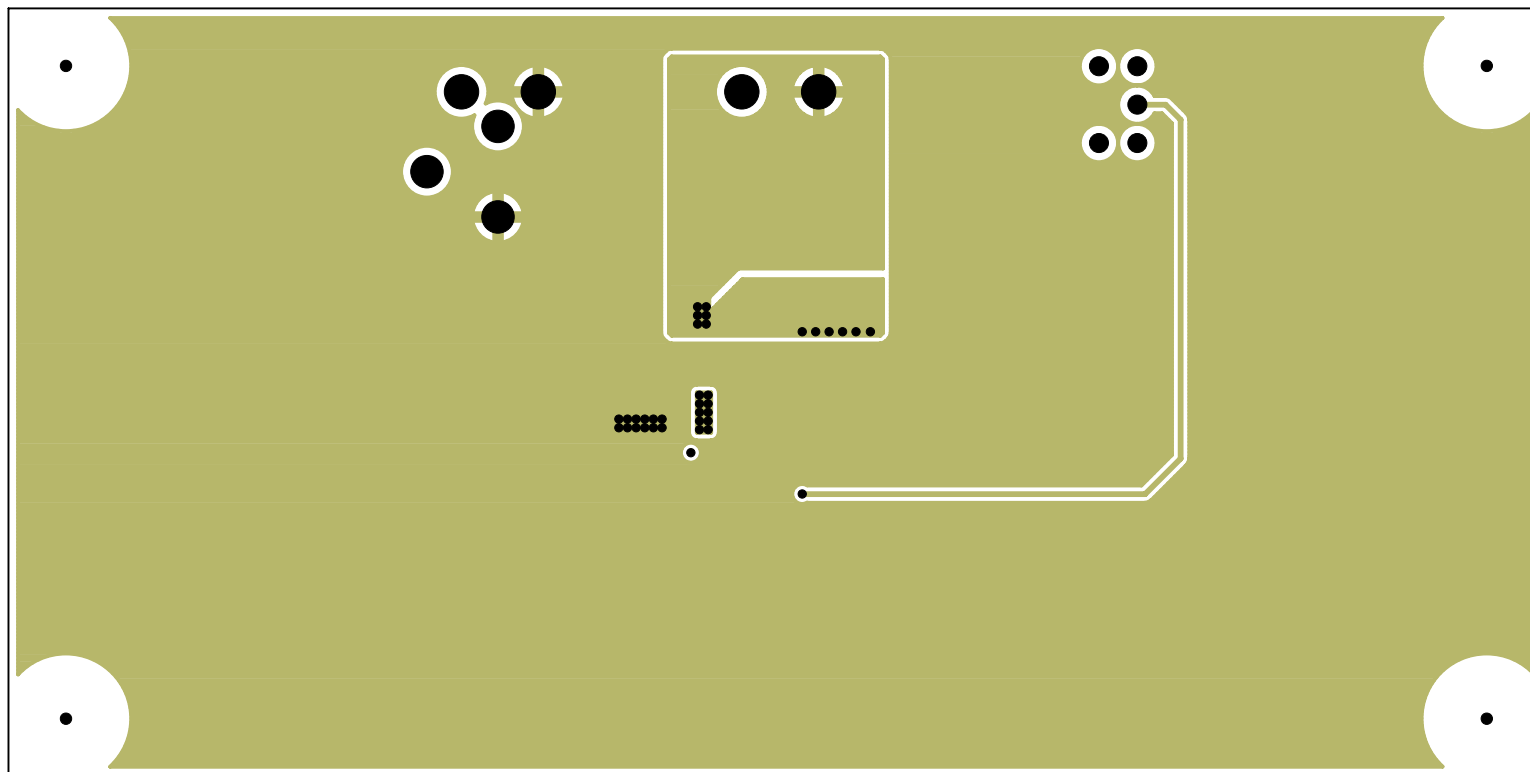


PRIMARY SIDE METAL

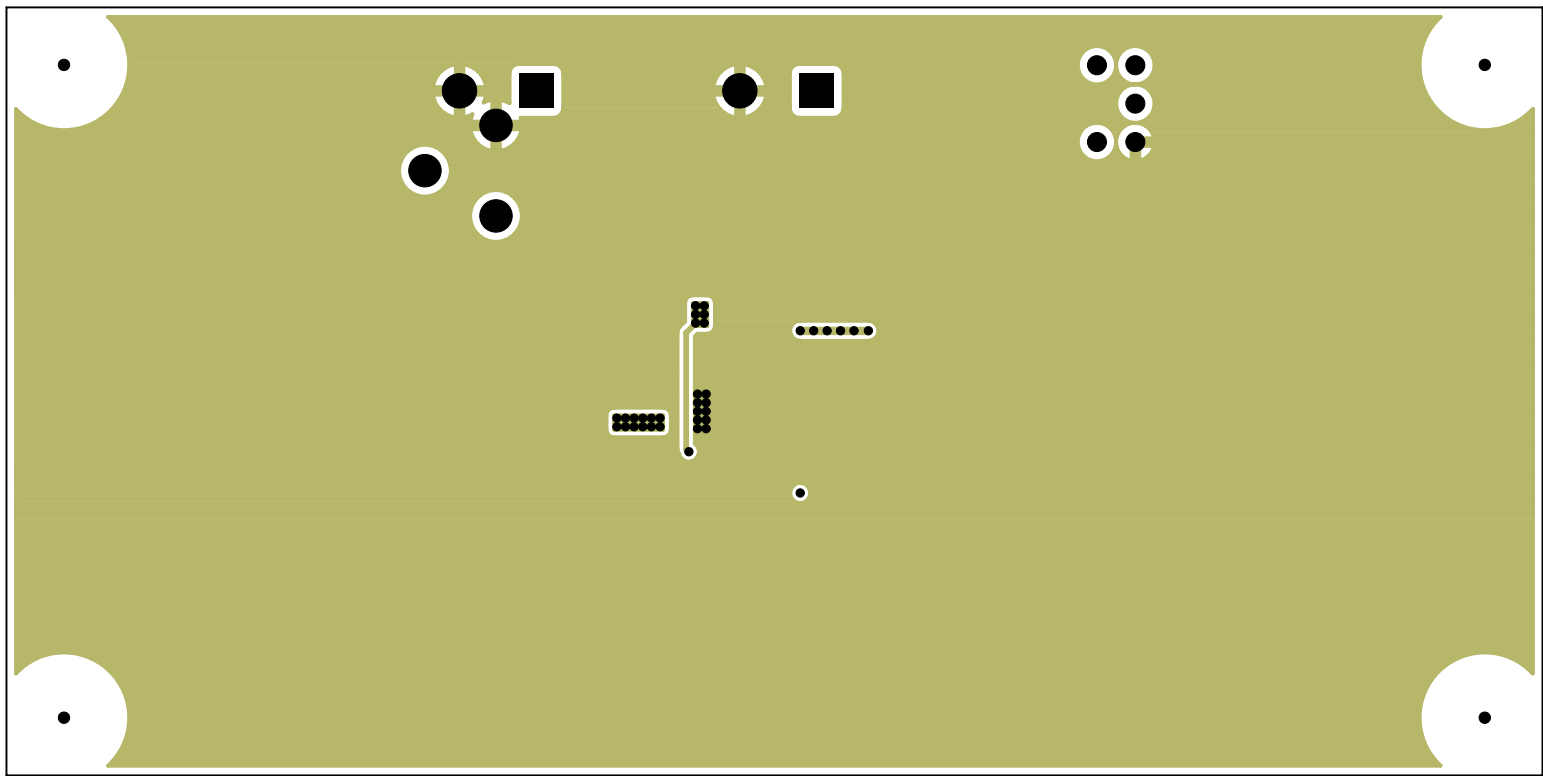


LAYER 2 METAL

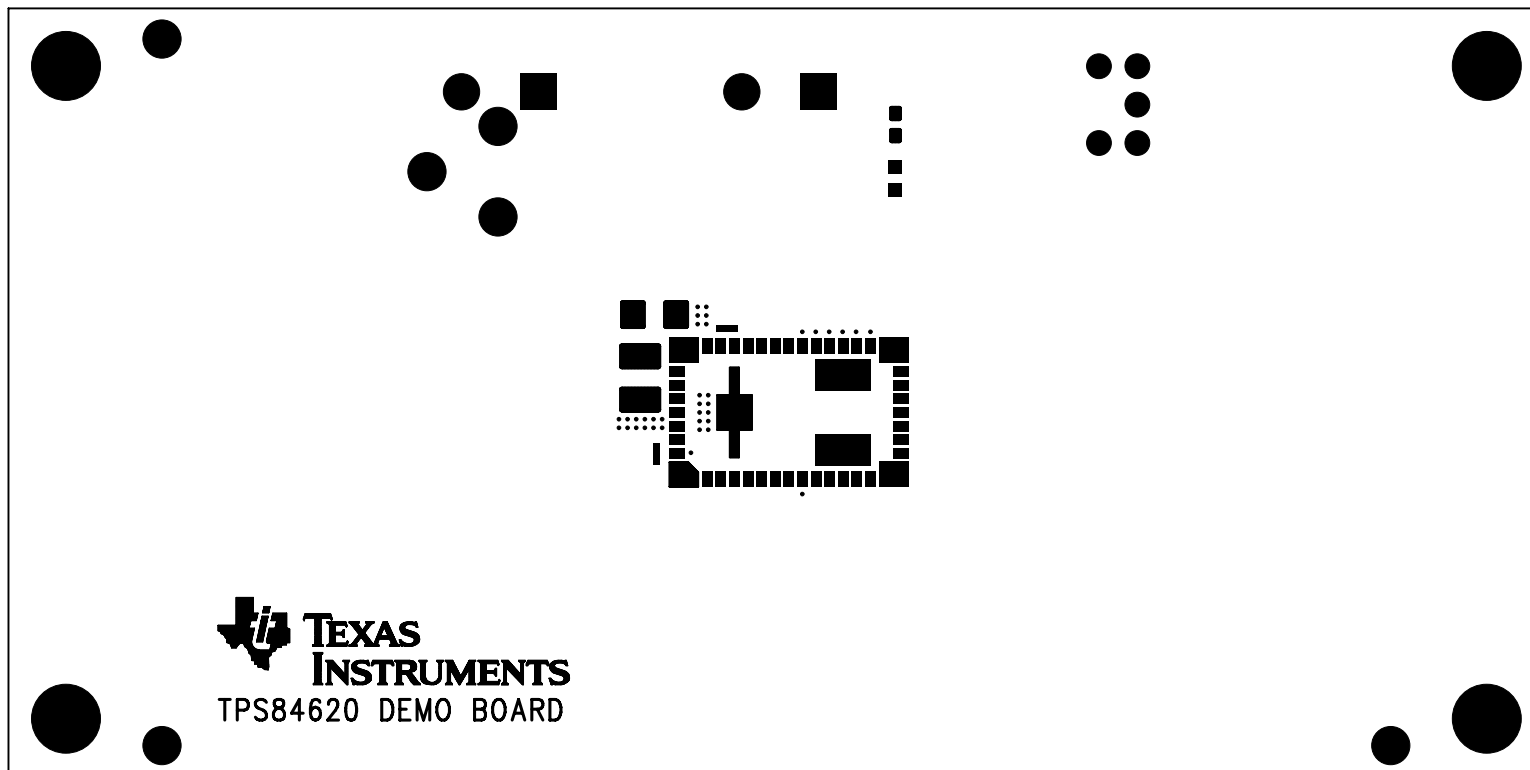
DESCRIPTION			SIZE	SCALE
PCB, FR-406, TPS84620 DEMO BOARD			A	2:1
DWG NO	REV	FILENAME	DO NOT SCALE DRAWING	
74-01011	1C	1011-1C.PCB	PAGE 4 OF 9	



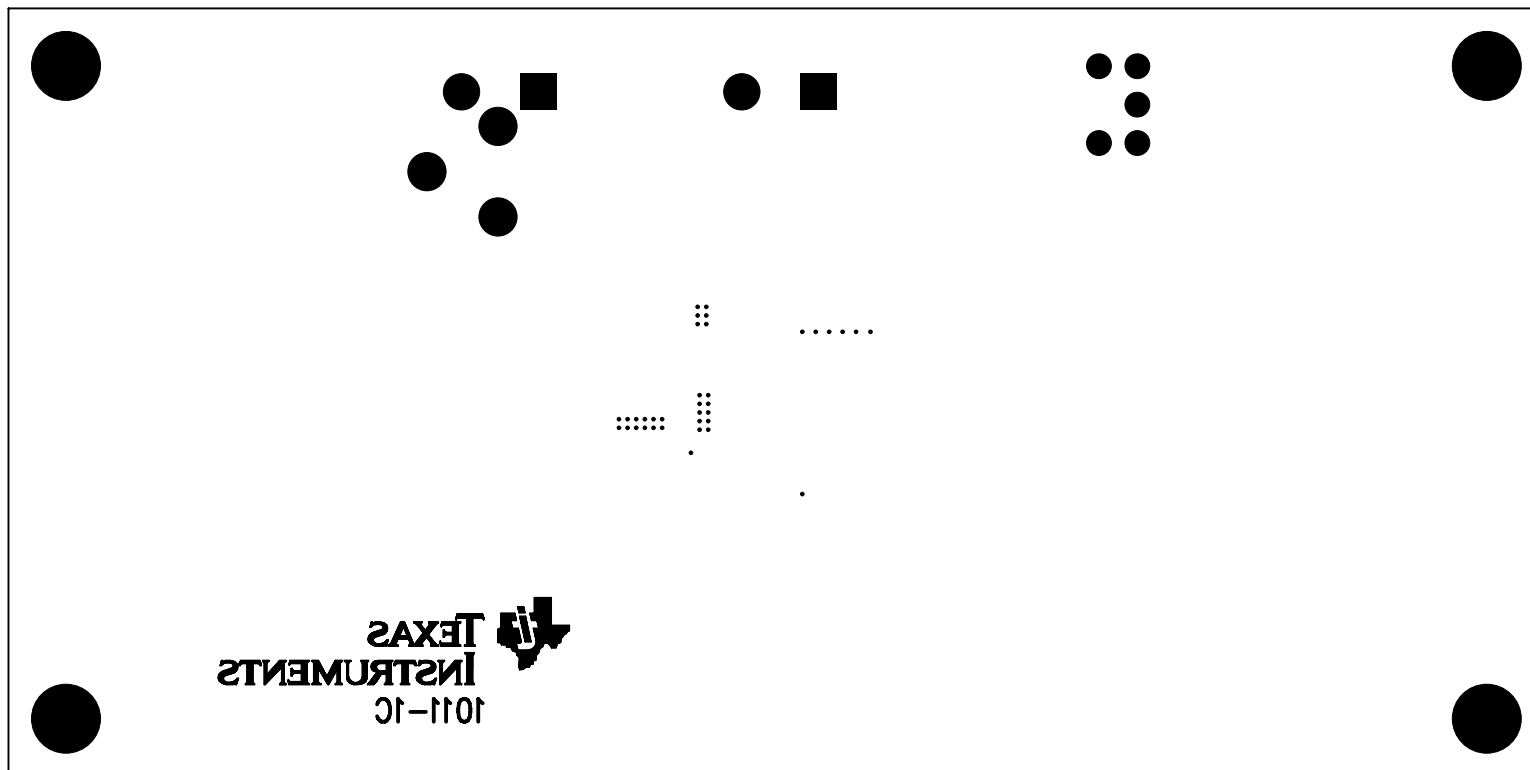
LAYER 3 METAL



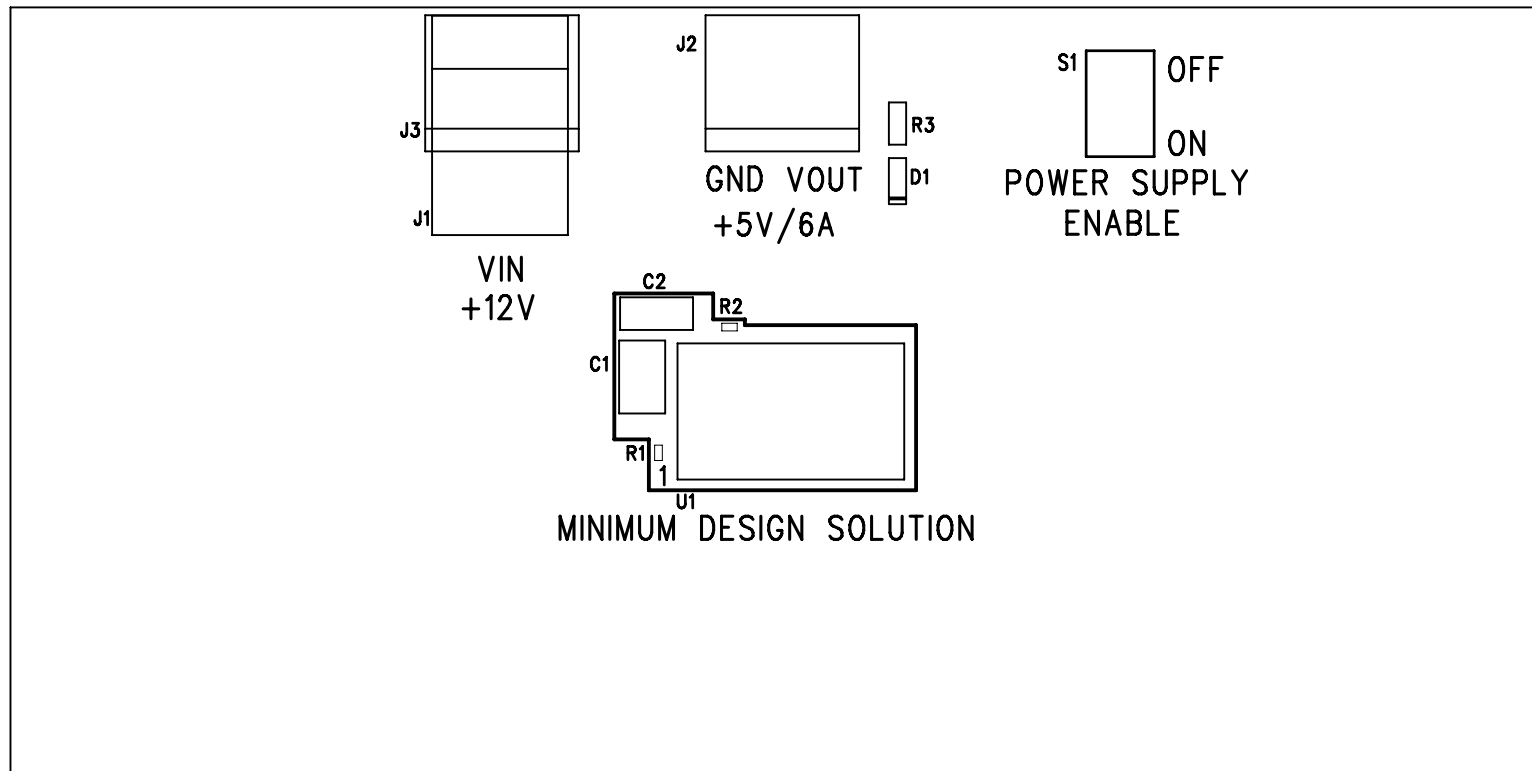
SECONDARY SIDE METAL



PRIMARY SIDE SOLDER MASK



SECONDARY SIDE SOLDER MASK



PRIMARY SIDE SILK SCREEN